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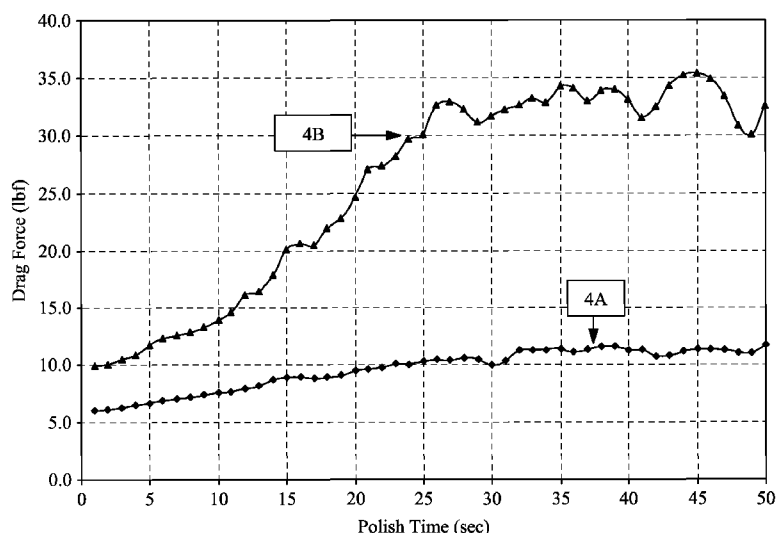
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[Continued on next page]

(54) Title: METAL-PASSIVATING CMP COMPOSITIONS AND METHODS

**FIG. 5**

(57) Abstract: The present invention provides chemical-mechanical polishing (CMP) compositions and methods for polishing copper- and/or silver-containing substrates. The compositions of the present invention comprise a particulate abrasive, a primary film-forming metal-complexing agent, and a secondary film-forming metal-passivating agent in an aqueous carrier. Methods of polishing a substrate with the compositions of the invention are also disclosed.



- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))* — *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments (Rule 48.2(h))*

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